

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below.

*Nils E. Pedersen*

Name of person signing certification

Signature

Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuto NISHIDA

Docket No. 00177/526327

Serial No. 09/331,763

Group Art Unit 3727

Filed June 25, 1999

Examiner J. Merek

METHOD AND APPARATUS FOR  
MOUNTING ELECTRONIC COMPONENT  
ON CIRCUIT BOARD

*Amdt*

*# 11/C*

*8/15/01*

*B. Ross*

AMENDMENT

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

In response to the Office Action of February 14, 2001, the period for response to which having been extended by three months to August 14, 2001, kindly amend the above-referenced U.S. patent application as follows:

IN THE SPECIFICATION

Please amend the specification as follows:

Please replace the paragraph beginning at page 29, line 7, to page 30, line 2, with the following rewritten paragraph:

C1  
In this case, the circuit board 4 is provided by a glass cloth base epoxy copper clad laminate board (glass epoxy board), a glass cloth base polyimide resin copper clad laminate board, or the like. These boards 4 have warp and undulation due to thermal hysteresis, cutting, and processing, meaning that their surfaces are not completely flat surfaces. Therefore, as shown

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975